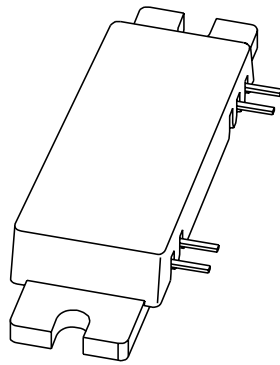


# DATA SHEET



## **BGY916** UHF amplifier module

Product specification  
Supersedes data of 1997 Jul 11

1998 May 27

# UHF amplifier module

# BGY916

### FEATURES

- 26 V nominal supply voltage
- 16 W output power into a load of 50 Ω with an RF drive power of 25 mW.

### APPLICATIONS

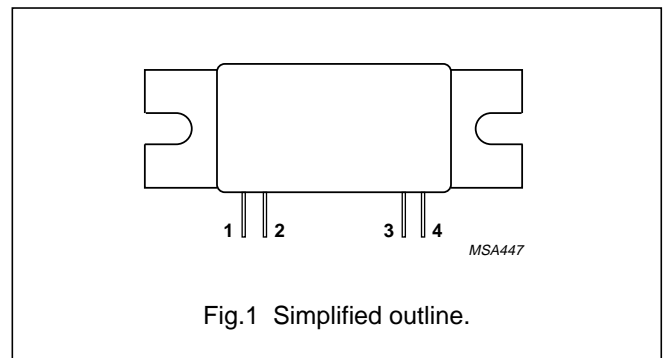
- Base station transmitting equipment operating in the 920 to 960 MHz frequency range.

### DESCRIPTION

The BGY916 is a three-stage UHF amplifier module in a SOT365A package. It consists of one NPN silicon planar transistor die and two silicon MOS-FET dies mounted on a metallized ceramic AlN substrate, together with matching and bias circuitry.

### PINNING - SOT365A

PIN	DESCRIPTION
1	RF input
2	V <sub>S1</sub>
3	V <sub>S2</sub>
4	RF output
flange	ground



### QUICK REFERENCE DATA

RF performance at T<sub>mb</sub> = 25 °C.

MODE OF OPERATION	f (MHz)	V <sub>S1</sub> ; V <sub>S2</sub> (V)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η (%)	Z <sub>S</sub> ; Z <sub>L</sub> (Ω)
CW	920 to 960	26	16	≥28	≥35	50

## UHF amplifier module

## BGY916

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>S1</sub>	DC supply voltage	–	28	V
V <sub>S2</sub>	DC supply voltage	–	28	V
P <sub>D</sub>	input drive power	–	80	mW
P <sub>L</sub>	load power	–	25	W
T <sub>stg</sub>	storage temperature	–30	+100	°C
T <sub>mb</sub>	operating mounting base temperature	–10	+90	°C

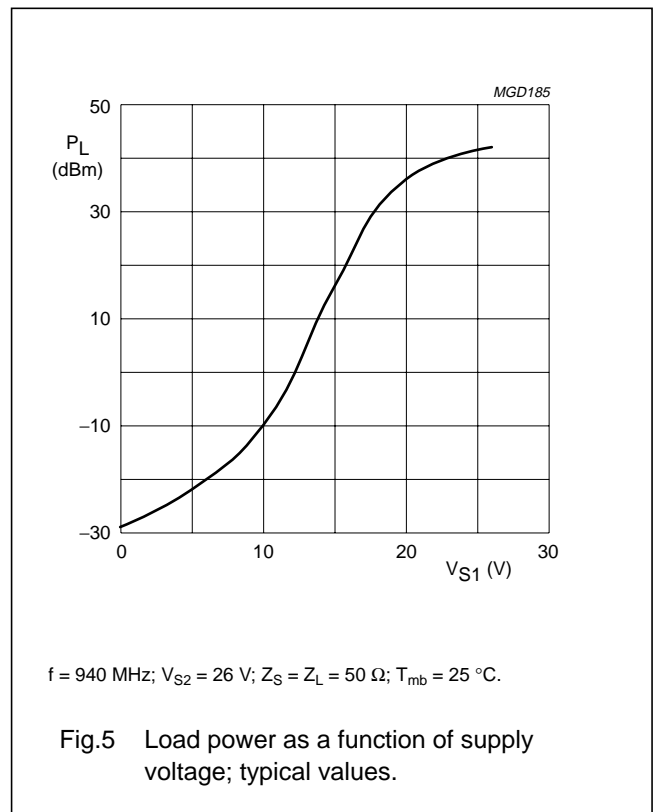
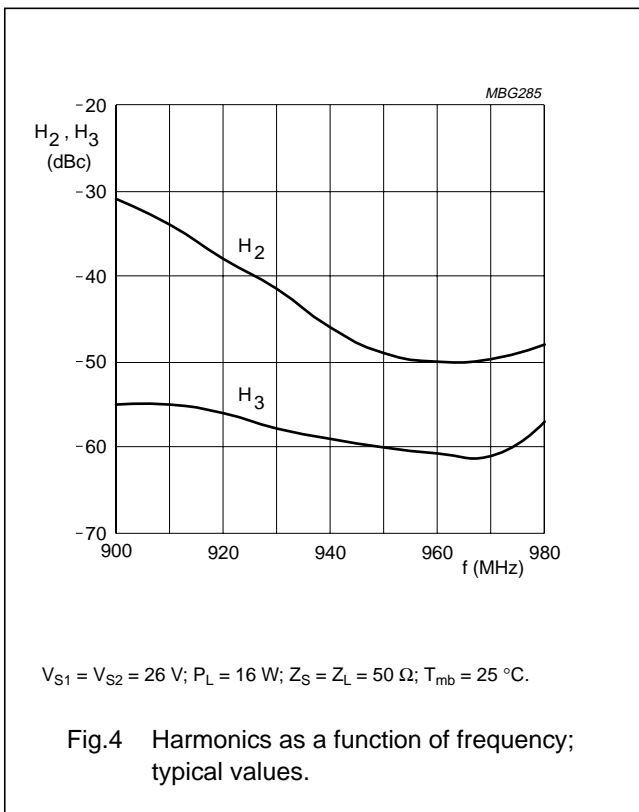
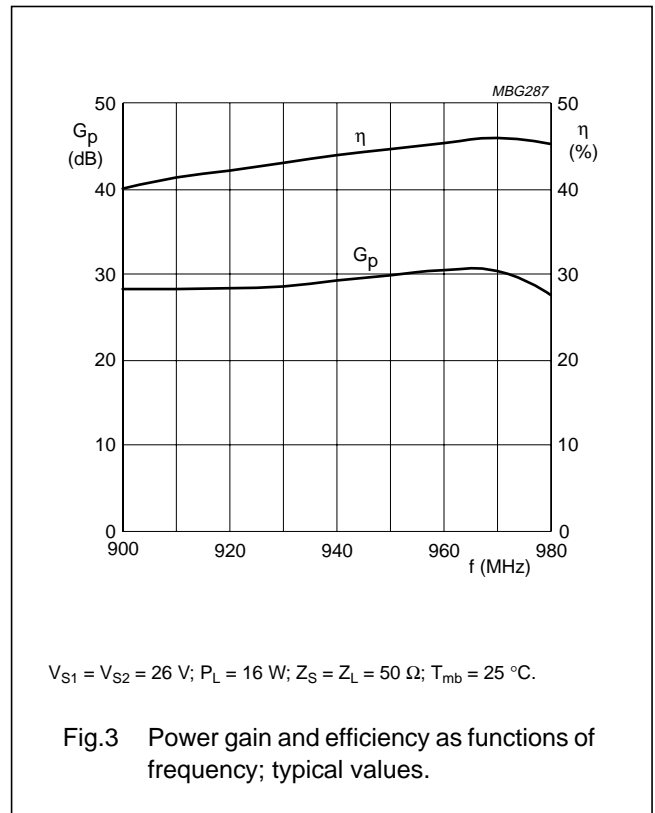
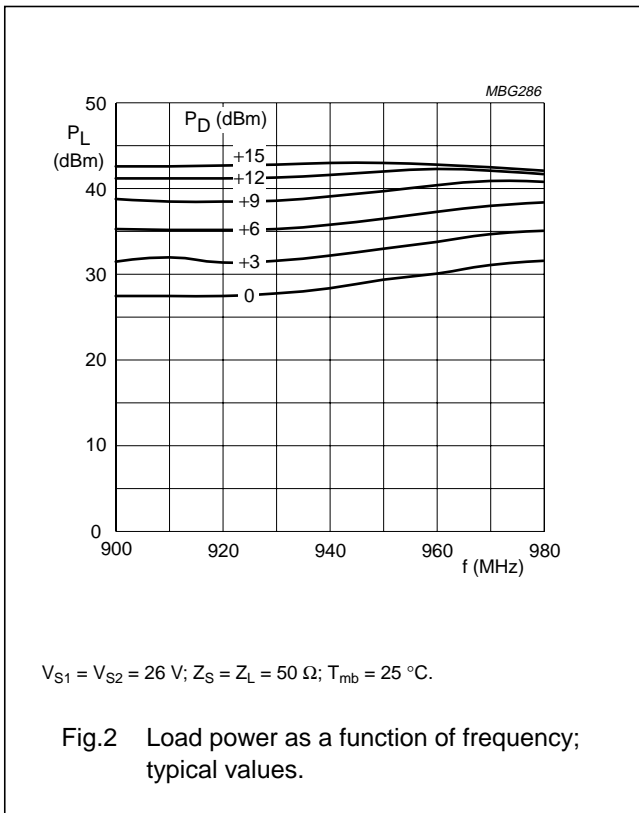
**CHARACTERISTICS**

T<sub>mb</sub> = 25 °C; V<sub>S1</sub> = V<sub>S2</sub> = 26 V; P<sub>L</sub> = 16 W; Z<sub>S</sub> = Z<sub>L</sub> = 50 Ω unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f	frequency		920	–	960	MHz
I <sub>S1</sub>	supply current		–	50	–	mA
I <sub>S2</sub>	supply current	P <sub>D</sub> < –60 dBm	–	150	–	mA
P <sub>L</sub>	load power		16	19	–	W
G <sub>p</sub>	power gain		28	30	32	dB
ΔG <sub>p</sub>	gain ripple	40 dB dynamic range at f = 920 to 960 MHz	–	1	4	dB
η	efficiency		35	40	–	%
H <sub>2</sub>	second harmonic		–	–47	–35	dBc
H <sub>3</sub>	third harmonic		–	–55	–45	dBc
VSWR <sub>in</sub>	input VSWR		–	1 : 1.5	2 : 1	
	isolation	V <sub>S1</sub> = 0	–	–	–40	dBm
	stability	VSWR ≤ 3 : 1 through all phases; V <sub>S2</sub> = 24 to 28 V	–	–	–60	dBc
	reverse intermodulation	P <sub>carrier</sub> = 16 W; P <sub>interference</sub> = 16 μW; f <sub>i</sub> = f <sub>c</sub> ±600 kHz	–	–68	–65	dBc
F	noise figure		–	5	8	dBc
B	AM bandwidth		2	–	–	MHz
	ruggedness	VSWR ≤ 5 : 1 through all phases	no degradation			

UHF amplifier module

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UHF amplifier module

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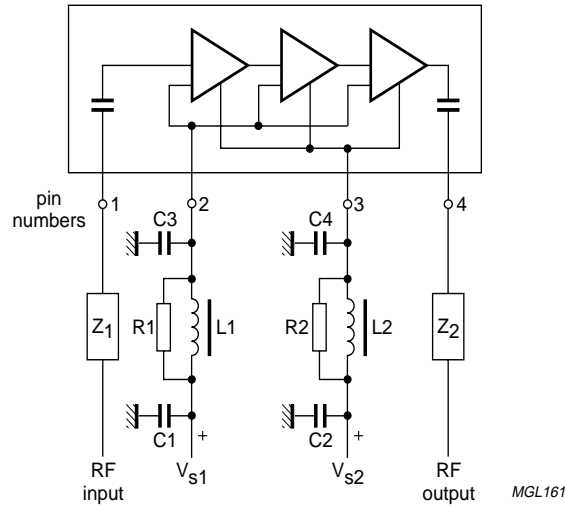
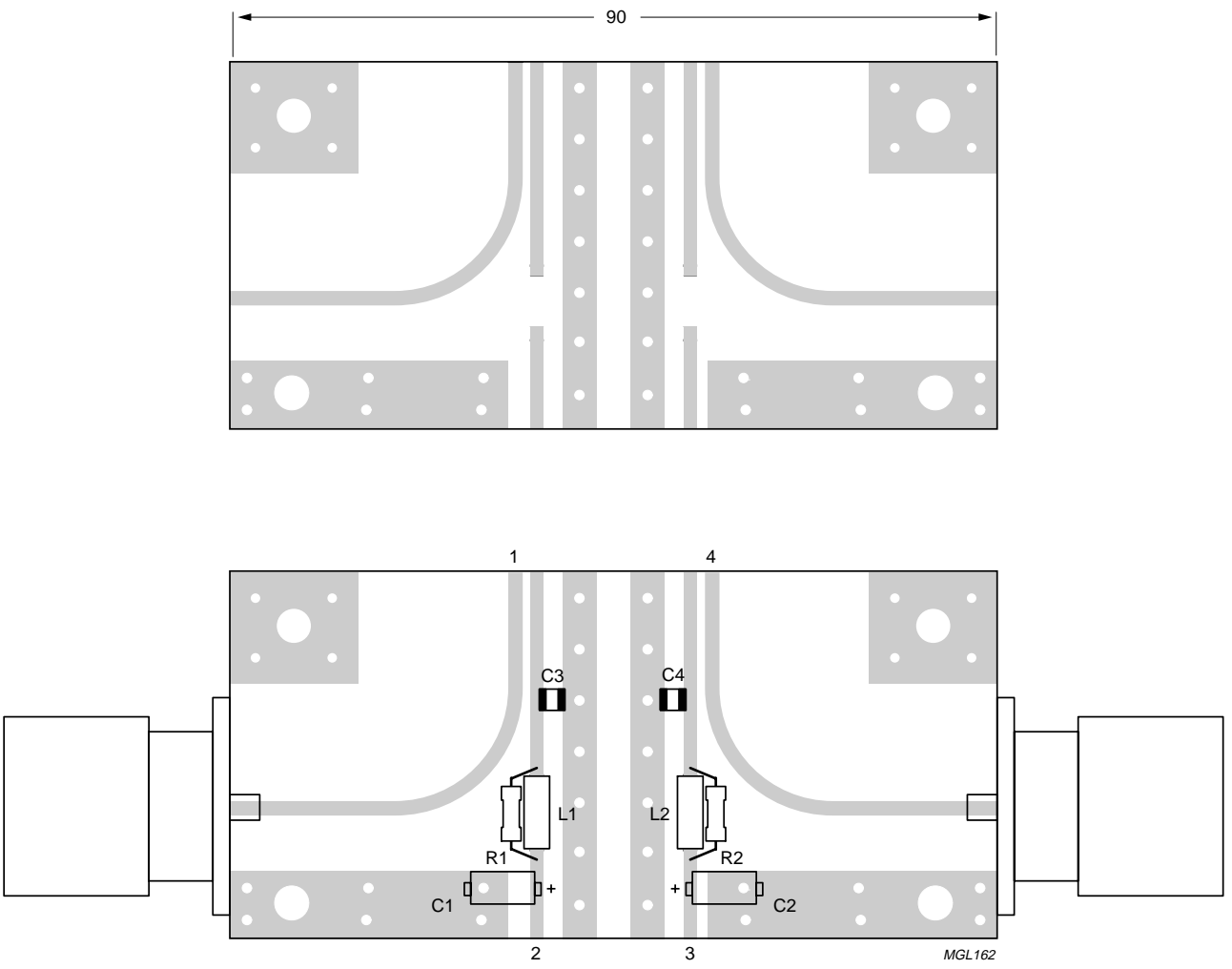


Fig.6 Test circuit.

# UHF amplifier module

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Dimensions in mm.

Fig.7 Printed-circuit board component layout.

## UHF amplifier module

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## List of components (see Figs 6 and 7)

COMPONENT	DESCRIPTION	VALUE	CATALOGUE NO.
C1, C2	electrolytic capacitor	10 $\mu$ F; 35 V	
C3, C4	multilayer ceramic chip capacitor	100 nF; 50 V	
L1, L2	Grade 4S2 Ferroxcube bead		4330 030 36300
R1, R2	metal film resistor	10 $\Omega$ ; 0.4 W	2322 195 13109
Z <sub>1</sub> , Z <sub>2</sub>	stripline; note 1	50 $\Omega$	–

## Note

- The striplines are on a double copper-clad printed-circuit board with epoxy dielectric ( $\epsilon_r = 4.5$ ); thickness = 1 mm.

## MOUNTING RECOMMENDATIONS

To ensure a good thermal contact and to prevent mechanical stresses when bolted down, the flatness of the mounting base is designed to be typically better than 0.1 mm. The mounting area of the heatsink should be flat and free from burrs and loose particles. The heatsink should be rigid and not prone to bowing under thermal cycling conditions. The thickness of a solid heatsink should be not less than 5 mm to ensure a rigid assembly.

A thin, even layer of thermal compound should be used between the mounting base and the heatsink to achieve the best possible contact thermal resistance. Excessive use of thermal compound will result in an increase in thermal resistance and possible bowing of the mounting base; too little will also result in poor thermal conduction.

The module should be mounted to the heatsink using 3 mm bolts with flat washers. The bolts should first be tightened to "finger tight" and then further tightened in alternating steps to a maximum torque of 0.4 to 0.6 Nm.

Once mounted on the heatsink, the module leads can be soldered to the printed-circuit board. A soldering iron may be used up to a temperature of 250 °C for a maximum of 10 seconds at a distance of 2 mm from the plastic cap.

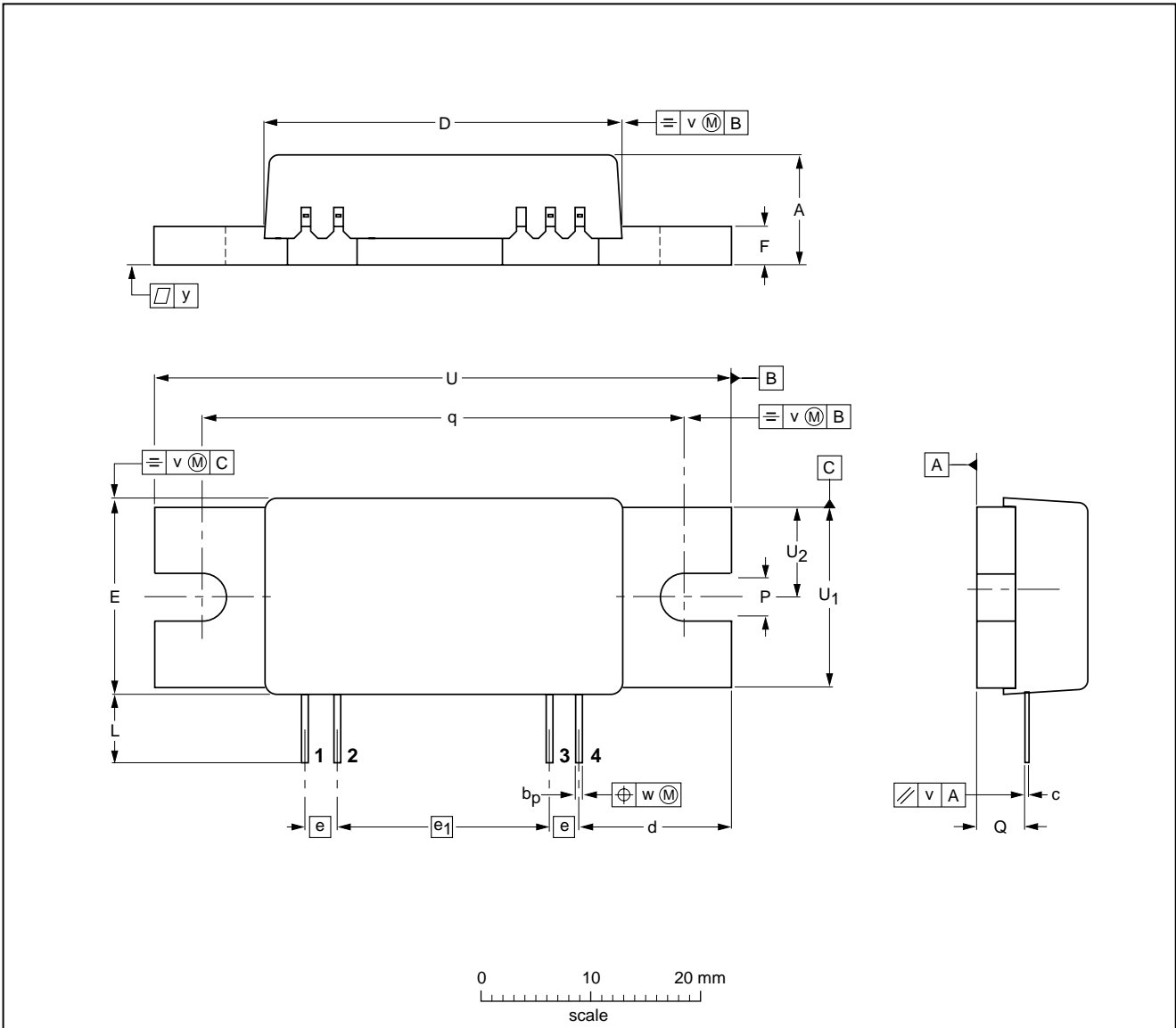
ESD precautions must be taken to protect the device from electrostatic damage.

UHF amplifier module

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PACKAGE OUTLINE

Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 4 in-line leads SOT365A



DIMENSIONS (mm are the original dimensions)

UNIT	A	b <sub>p</sub>	c	D	d	E	e	e <sub>1</sub>	F	L	P	Q	q	U	U <sub>1</sub>	U <sub>2</sub>	v	w	y
mm	9.5 9.0	0.56 0.46	0.3 0.2	30.1 29.9	12.8 12.6	18.6 18.4	2.54	17.78	3.25 3.15	6.5 6.1	4.1 3.9	4.0 3.8	40.74 40.54	48.0 48.4	15.4 15.2	7.75 7.55	0.2	0.25	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT365A						97-05-25



## UHF amplifier module

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**DEFINITIONS**

<b>Data Sheet Status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	

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**NOTES**

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**NOTES**

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